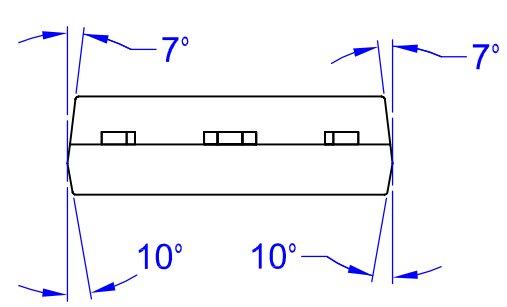
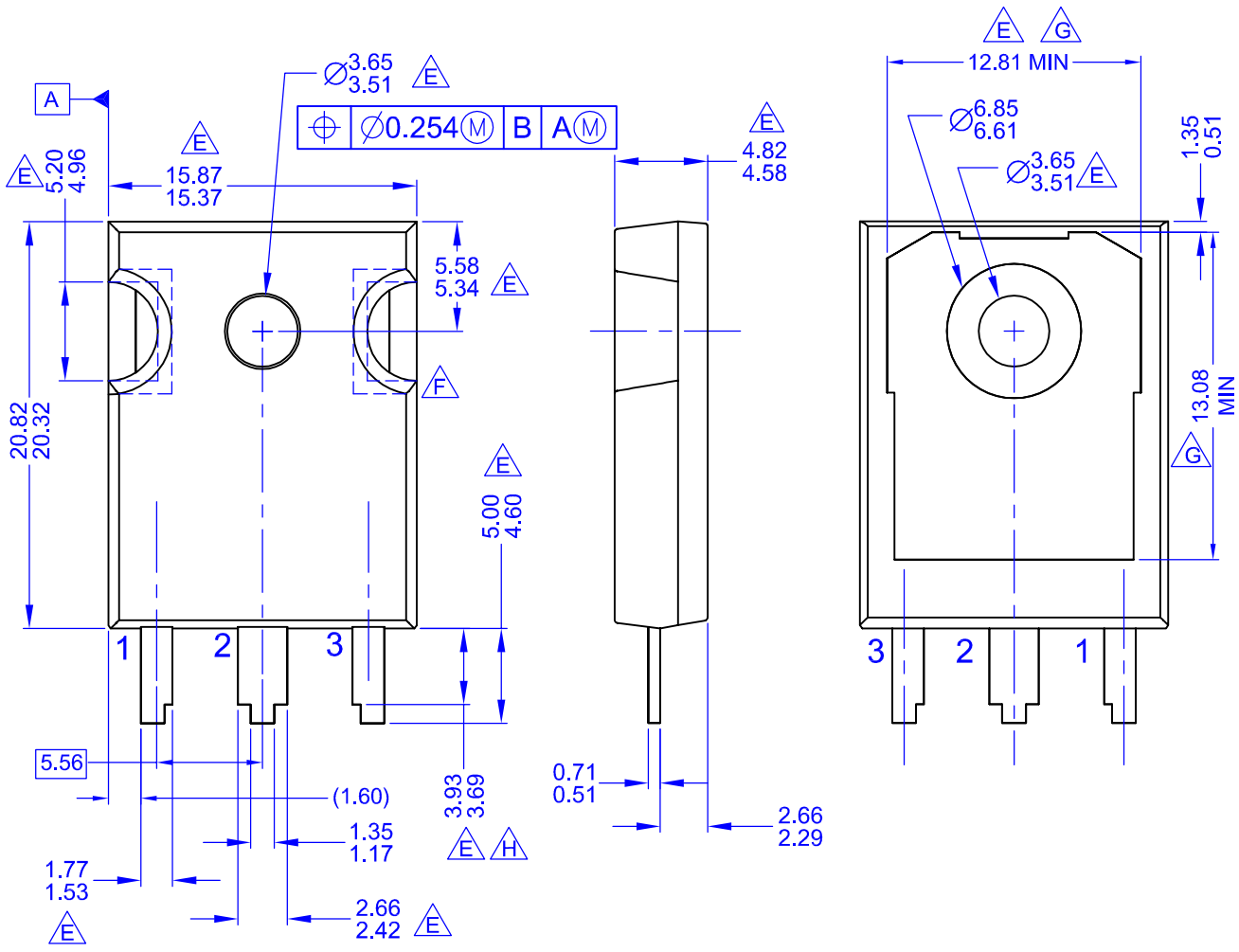


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REVISIONS			
NUMBR	DESCRIPTION	DATE	BY/SITE
1	RELEASE TO DOCUMENT CONTROL	17MAR08	S.D.LEE/SUZHOU



- NOTES: UNLESS OTHERWISE SPECIFIED
- A. PACKAGE REFERENCE: JEDEC TO-247, VARIATION AB
  - B. ALL DIMENSIONS ARE IN MILLIMETERS.
  - C. DRAWING CONFORMS TO ASME Y14.5M - 1994
  - D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
  - DOES NOT COMPLY TO JEDEC STANDARD VALUE
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  - THERMAL PAD COUNTOUR OPTIONAL WITHIN HEATSINK DIMENSIONS
  - LEAD FINISH UNCONTROLLED ON LEAD SHOULDER
  - I. DRAWING NUMBER AND REVISION: MKT-TO247B03rev1

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR™		
DRAWN: CHRISTOPHER DAI	17MAR2008	TO247, MOLDED, 3LD, JEDEC VARIATION AB, STRAIGHT SHORT LEAD		
CHECKED: FRED REN				
APPROVED: S.D. LEE				
HOWARD ALLEN				
PROJECTION 	SCALE 1:1	SIZE NA	DRAWING NUMBER MKT-TO247B03	REV 1
		FORMERLY: N/A		SHEET : 1 OF 1